Sil-Pad® 900S

High Performance Insulator for Low-Pressure Applications

Features and Benefits

- Thermal impedance: 0.61°C-in²/W (@50 psi)
- · Electrically isolating
- · Low mounting pressures
- Smooth and highly compliant surface
- General-purpose thermal interface material solution



The true workhorse of the Sil-Pad product family, Sil-Pad 900S thermally conductive insulation material is designed for a wide variety of applications requiring high thermal performance and electrical isolation. These applications also typically have low mounting pressures for component clamping.

Sil-Pad 900S material combines a smooth and highly compliant surface characteristic with high thermal conductivity. These features optimize the thermal resistance properties at low pressure.

Applications requiring low component clamping forces include discrete semiconductors (TO-220,TO-247 and TO-218) mounted with spring clips. Spring clips assist with quick assembly and apply a limited amount of force to the semiconductor. The smooth surface texture of Sil-Pad 900S minimizes interfacial thermal resistance and maximizes thermal performance.

TYPICAL PROPERTIES OF SIL-PAD 900S						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Pink		Pink		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.009		0.229		ASTM D374	
Hardness (Shore A)	92		92		ASTM D2240	
Elongation (%45° to Warp and Fill)	20		20		ASTM D412	
Tensile Strength (psi) / (MPa)	1300		9		ASTM D412	
Continuous Use Temp (°F) / (°C)	-76 to 356		-60 to 180		_	
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	5500		5500		ASTM D149	
Type 3 Electrodes	8300		8300		ASTM D149	
Dielectric Constant (1000 Hz)	6.0		6.0		ASTM D150	
Volume Resistivity (Ohm-meter)	1010		1010		ASTM D257	
Flame Rating	V-O		V-O		U.L. 94	
THERMAL						
Thermal Conductivity (W/m-K)	1.6		1.6		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Pressure (psi)		10	25	50	100	200
TO-220 Thermal Performance (°C/W)		3.96	3.41	2.90	2.53	2.32
Thermal Impedance (°C-in²/W) (1)		0.95	0.75	0.61	0.47	0.41
I) The ASTM D5470 (Bergquist modified) test fixture	e was used.The	recorded va	lue includes in	terfacial therm	nal resistance.	hese

values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

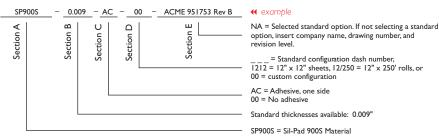
Typical Applications Include:

- Power supplies
- Automotive electronics
- Motor controls
- Power semiconductors

Configurations Available:

- Sheet form, die-cut parts, and roll form
- With or without pressure sensitive adhesive

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others

Standard Options